

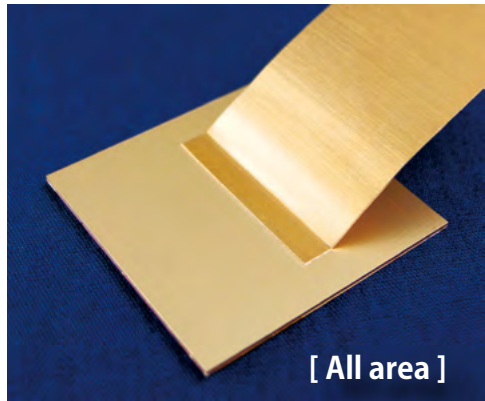


SoundBonding application



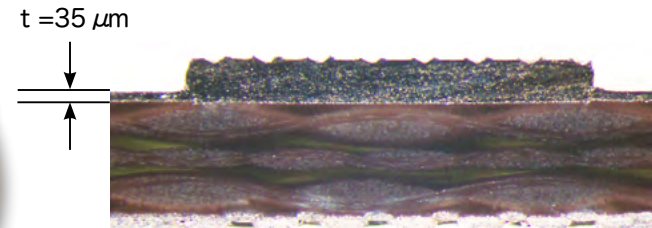
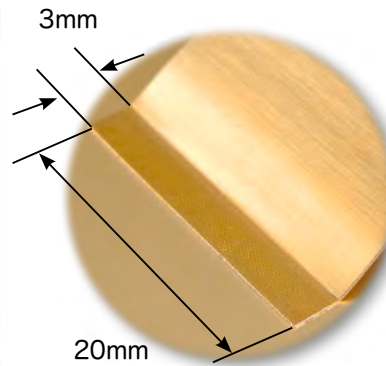
〈FFC on FR4 substrate〉

All area / 5 points bonding at a time

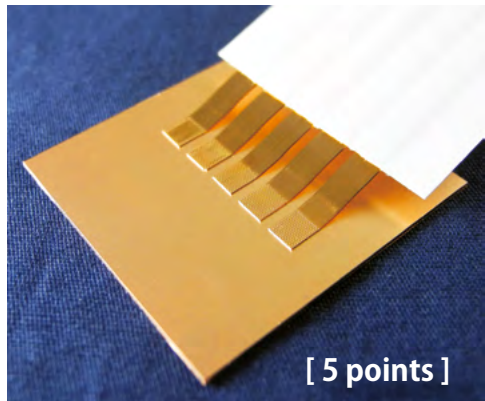


[All area]

FR4 substrate : $t = 0.3\text{mm}$, Cu layer : $t = 35\ \mu\text{m}$
Cu foil : $t = 0.1\text{mm}$

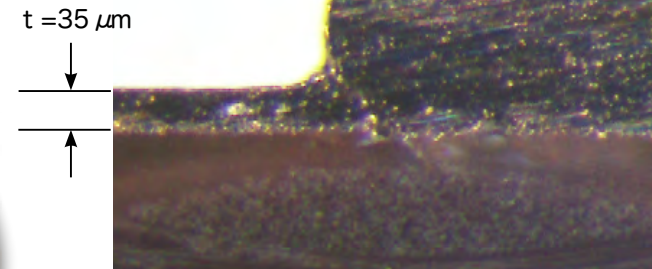
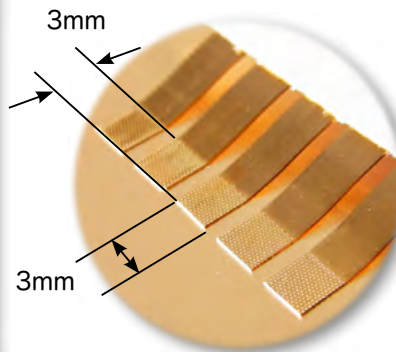


[The cross section]



[5 points]

FR4 substrate : $t = 0.3\text{mm}$, Cu layer : $t = 35\ \mu\text{m}$
Cu foil : $t = 0.15\text{mm}$



[The expanded cross section]